

CLAIMS

1. A method for manufacturing an intermediate electronic device for a device having an electronic module covered with a cover sheet or layer, said method comprising a step of forming a carrier body comprising:

- a cavity formed in the carrier body,
- an electrical circuit comprising at least one electrical interconnection area inside the cavity,
- an electronic module comprising a protective coating and at least one connection pad connecting said interconnection area, said electronic module being disposed in the cavity and covered by a cover sheet or layer from outside the cavity, and
- a space or gap existing at the interface between the module and the carrier body, oriented substantially perpendicular to a principal surface of the carrier body, and emerging on the surface of the carrier body,

wherein a flexible or elastic material is arranged in the device so as to at least partially fill or cover said space or gap oriented substantially perpendicular to the principal surface of the carrier body.

2. A method according to claim 1, wherein the flexible material comprises a conductive connection material arranged and compressed in the device so as to connect the module to the circuit and to flow into said space or gap in order to at least partially fill it.

3. A method according to claim 2, wherein the conductive material is of the anisotropic type.

4. A method according to claim 3, wherein the anisotropic material surrounds the module.
5. A method according to claim 4, wherein the anisotropic material comprises a patch made from flexible or elastic material covering the interface.
6. A method according to claim 5, wherein the anisotropic material comprises at least one cover sheet on top of or below said patch or the gap.
7. An intermediate electronic device for a device having an electronic module covered by a cover sheet or layer, comprising:
- a carrier body,
 - a cavity formed in the carrier body,
 - an electrical circuit comprising at least one electrical interconnection area inside the cavity,
 - an electronic module comprising a protective coating and at least one connection pad connecting said interconnection area, said electronic module being disposed in the cavity and covered by a cover sheet or layer from outside the cavity,
 - a space or gap existing at the interface between the module and the carrier body, oriented substantially perpendicular to a principal surface of the carrier body and emerging on the surface of the carrier body, an intermediate electronic device, and emerging on the surface of the carrier body, and a flexible or elastic material arranged in the device so as to at least partially fill or cover said space or gap oriented substantially perpendicular to the principal surface of the carrier body.

8. A device according to claim 7, wherein the flexible material comprises a conductive connection material arranged and compressed in the device so as to connect the module to the circuit and to flow into said space or gap in order to fill it at least partially.

9. A device according to claim 8, wherein the conductive material is anisotropic.

10. An electronic device comprising the intermediate device according to claim 7, wherein said cover sheet or layer covers said space or gap existing at the interface between the module and the carrier body.